

Product Change Notice (PCN)

Date: 12/28/2022

PCN Number: PCN-0454852R-01

To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

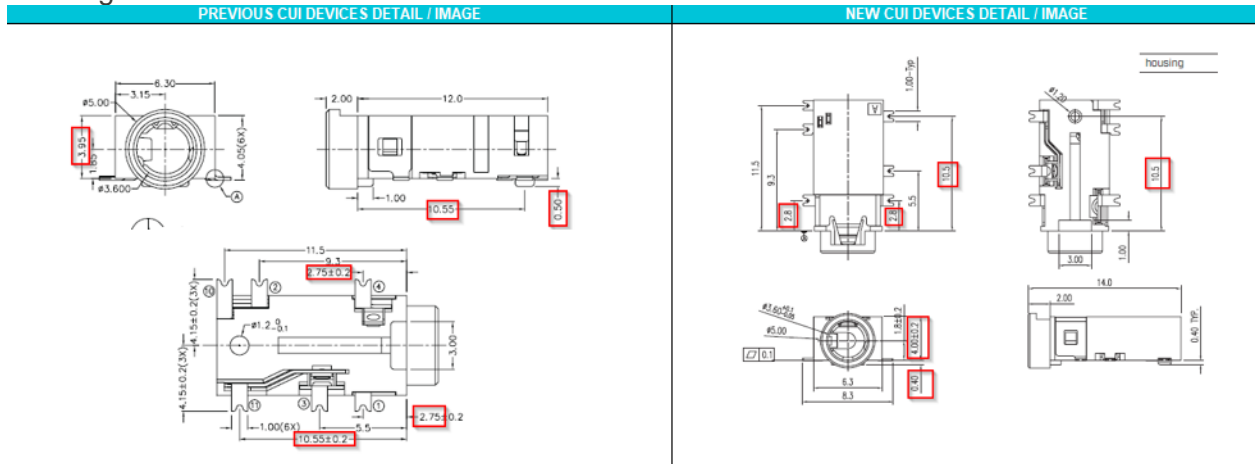
Product(s) Affected:

SJ2-35954A-SMT-TR, SJ2-35954B-SMT-TR, SJ2-35954D-SMT-TR

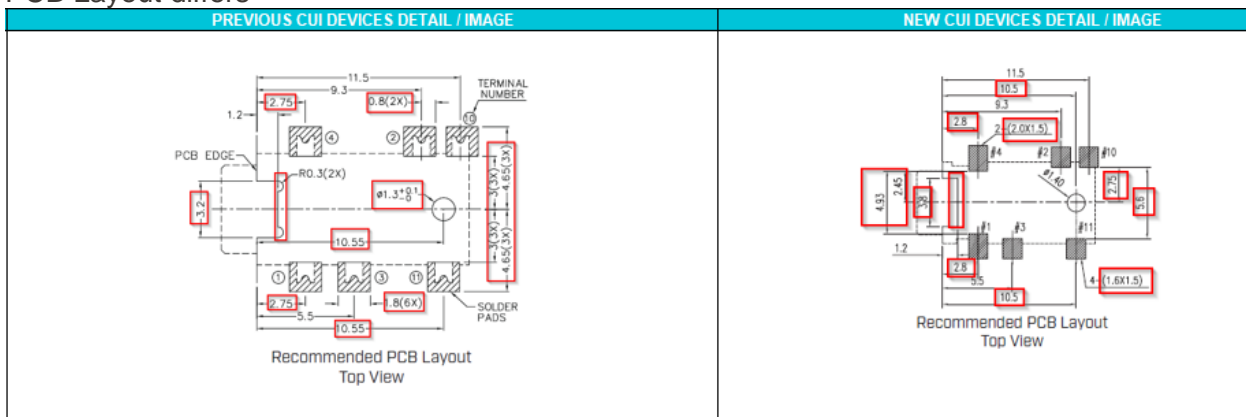
Reason(s) for Change: *Manufacturing process improvements*

Description of Change:

- Housing and Terminal Differs



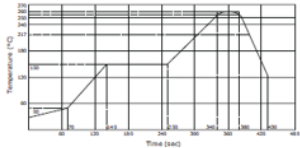
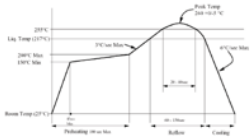
2. PCB Layout differs



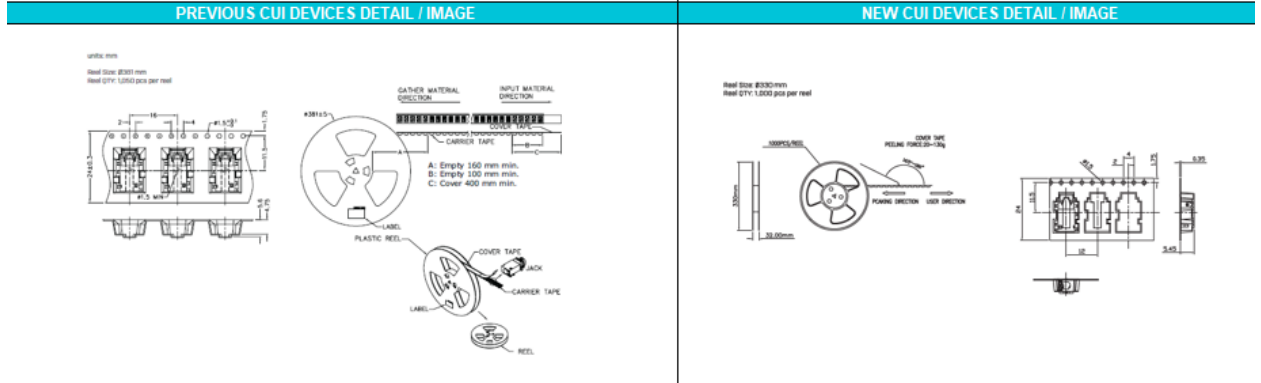
3. Housing material differs

	PREVIOUS CUI DEVICES DETAIL / IMAGE		NEW CUI DEVICES DETAIL / IMAGE	
	MATERIAL	PLATING	MATERIAL	PLATING
terminal 1	copper alloy	gold flash	copper alloy t=0.20	gold flash over nickel
terminal 2	copper alloy	gold flash	copper alloy t=0.25	gold flash over nickel
terminal 3	copper alloy	gold flash	copper alloy t=0.20	gold flash over nickel
terminal 4	copper alloy	gold flash	copper alloy t=0.25	gold flash over nickel
terminal 10	copper alloy	gold flash	copper alloy t=0.25	gold flash over nickel
terminal 11	copper alloy	gold flash	copper alloy t=0.20	gold flash over nickel
plastic	PA10T		PA9T (UL94V-0)	black

4. Reflow Soldering Difference

	PREVIOUS CUI DEVICES DETAIL / IMAGE	NEW CUI DEVICES DETAIL / IMAGE																																										
SOLDERABILITY	<table border="1"> <thead> <tr> <th>parameter</th> <th>conditions/description</th> <th>min</th> <th>typ</th> <th>max</th> <th>units</th> </tr> </thead> <tbody> <tr> <td>refl storage</td> <td>at relative humidity <80%</td> <td></td> <td>40</td> <td></td> <td>°C</td> </tr> <tr> <td>reflow soldering¹</td> <td>see reflow profile</td> <td>255</td> <td>260</td> <td>265</td> <td>°C</td> </tr> <tr> <td>drying conditions²</td> <td>parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours</td> <td></td> <td></td> <td></td> <td></td> </tr> </tbody> </table> <p>Note: 3. Must reflow solder within 72 hours from opening vacuum packaging at a temperature <30°C & relative humidity <60%. 4. When exceeding floor life by >10 hours.</p> 	parameter	conditions/description	min	typ	max	units	refl storage	at relative humidity <80%		40		°C	reflow soldering ¹	see reflow profile	255	260	265	°C	drying conditions ²	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours					<table border="1"> <thead> <tr> <th>parameter</th> <th>conditions/description</th> <th>min</th> <th>typ</th> <th>max</th> <th>units</th> </tr> </thead> <tbody> <tr> <td>refl storage</td> <td>5-25°C, 20-75% humidity</td> <td></td> <td>40</td> <td></td> <td>°C</td> </tr> <tr> <td>reflow soldering</td> <td>see reflow profile</td> <td>255</td> <td>260</td> <td></td> <td>°C</td> </tr> </tbody> </table> <p>Note: 1. CUI Devices recommends usage of the product within 24 hours after TSS is opened. After 24 hours, CUI Devices recommends drying the parts prior to use.</p> 	parameter	conditions/description	min	typ	max	units	refl storage	5-25°C, 20-75% humidity		40		°C	reflow soldering	see reflow profile	255	260		°C
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5. Tape and reel packaging differs



Affected Date Code: **11/15/2022**

Product Availability: **Channel availability mid Q4**

Additional Information:

PCN Approval:

Operations/Quality



Product Management



Nick Wolfe 11/21/2022